

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

Characteristic	Symbol	B520C	B530C	B540C	B550C	B560C	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	30	40	50	60	V
RMS Reverse Voltage	V _{R(RMS)}	14	21	28	35	42	V
Average Rectified Output Current	lo	5.0				Α	
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half-Sine-Wave Superimposed on Rated Load	I _{FSM}	100			Α		
Electrostatic Discharge	HBM	4000			V		
Electrostatic Discharge	MM	400			V		
Electrostatic Discharge	CDM	1			K۷		

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Terminal	R _{OJT}	10	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R _{OJA}	50	°C/W
Thermal Resistance, Junction to Ambient (Note 7)	R _{OJA}	115	°C/W
Thermal Resistance, Junction to Ambient (Note 8)	R _{OJA}	30	°C/W
Operating Temperature Range	TJ	-55 to +150	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	B520C, B530C, B540C B550C, B560C	\/-	1 1	0.475 0.575	0.55 0.70	V	I _F = 5.0A, T _A = +25°C
Leakage Current (Note 7)		I _R	_		0.5 20	mA	@ Rated V_R , $T_A = +25$ °C @ Rated V_R , $T_A = +100$ °C
Total Capacitance		C _T		_	300	pF	$V_R = 4V, f = 1MHz$
Switching Speed t _{RR}		t _{RR}		16		ns	I _F =0.5A, I _R =1A, I _{RR} =0.25A (RG1)

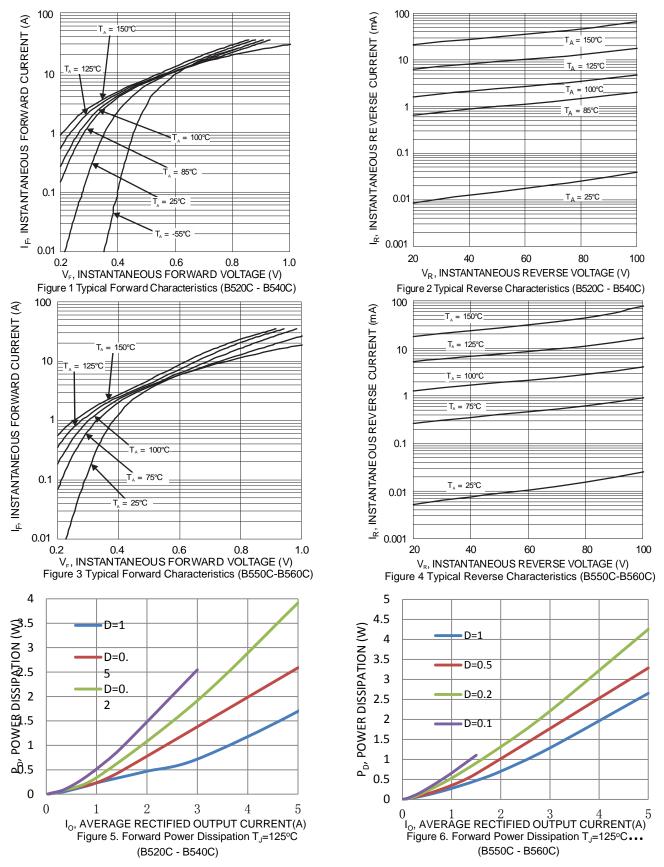
Notes: 6. Thermal Resistance: Junction to ambient, unit mounted on PC board with 8.0mm² (0.033mm thick) copper pads as heatsink.

^{7.} MRP FR-4 PCB, 2oz.

^{8.} With 50mm × 50mm × 23mm Al heatsink.

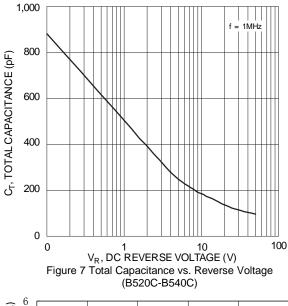
^{9.} Short duration pulse test used to minimize self-heating effect.





Note: 8. Device mounted on FR-4 substrate, 1" x 1", 2oz, single-sided, PCBs with 0.56" x 0.73" copper pad.





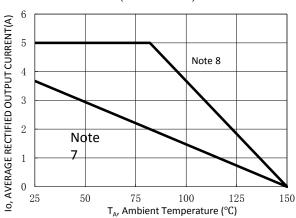


Figure 9. DC Forward Current Derating

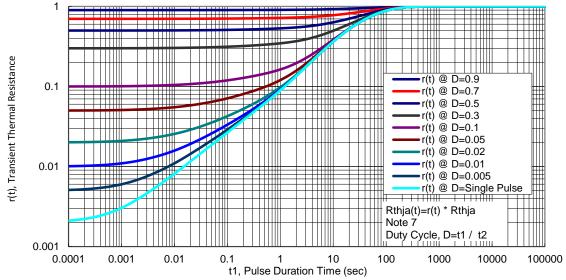


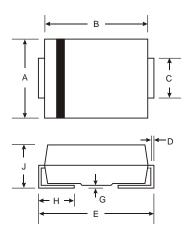
Figure 10: Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SMC

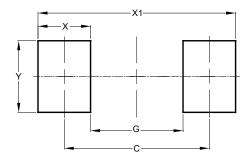


SMC					
Dim	Min	Max			
Α	5.59	6.22			
В	6.60	7.11			
U	2.75	3.18			
D	0.15	0.31			
ш	7.75	8.13			
G	0.10	0.20			
Η	0.76	1.52			
J	2.00	2.50			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SMC



Dimensions	Value (in mm)
С	6.90
G	4.40
Х	2.50
X1	9.40
Y	3.30



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